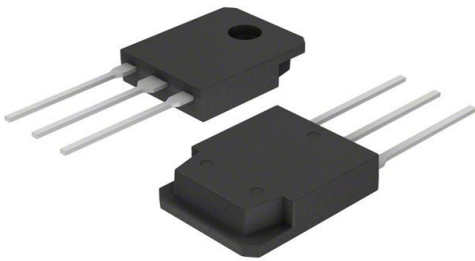


IXTH1N200P3 Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

| | |
|------------------------------|---|
| DiGi Electronics Part Number | IXTH1N200P3-DG |
| Manufacturer | IXYS |
| Manufacturer Product Number | IXTH1N200P3 |
| Description | MOSFET N-CH 2000V 1A TO247 |
| Detailed Description | N-Channel 2000 V 1A (Tc) 125W (Tc) Through Hole TO-247 (IXTH) |



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

IXTH1N200P3

Series:

Polar P3™

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

2000 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

4V @ 250µA

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-247 (IXTH)

Base Product Number:

IXTH1

Manufacturer:

IXYS

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

1A (Tc)

Rds On (Max) @ Id, Vgs:

400hm @ 500mA, 10V

Gate Charge (Qg) (Max) @ Vgs:

23.5 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

646 pF @ 25 V

Power Dissipation (Max):

125W (Tc)

Mounting Type:

Through Hole

Package / Case:

TO-247-3

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



High Voltage Power MOSFET

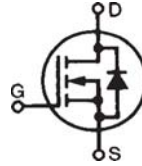
IXTA1N200P3HV
IXTH1N200P3HV
IXTH1N200P3

$$V_{DSS} = 2000V$$

$$I_{D25} = 1.0A$$

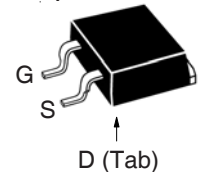
$$R_{DS(on)} \leq 40\Omega$$

N-Channel Enhancement Mode

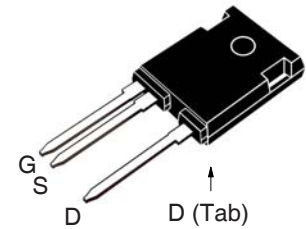


| Symbol | Test Conditions | Maximum Ratings | |
|---------------|---|-------------------|------------------|
| V_{DSS} | $T_J = 25^\circ\text{C}$ to 150°C | 2000 | V |
| V_{DGR} | $T_J = 25^\circ\text{C}$ to 150°C , $R_{GS} = 1M\Omega$ | 2000 | V |
| V_{GSS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 1.0 | A |
| I_{D110} | $T_C = 110^\circ\text{C}$ | 0.6 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, Pulse Width Limited by T_{JM} | 3.0 | A |
| P_D | $T_C = 25^\circ\text{C}$ | 125 | W |
| T_J | | - 55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | - 55 ... +150 | $^\circ\text{C}$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ\text{C}$ |
| T_{SOLD} | 1.6 mm (0.062in.) from Case for 10s | 260 | $^\circ\text{C}$ |
| F_C | Mounting Force (TO-263HV) | 10..65 / 22..14.6 | N/lb |
| M_d | Mounting Torque (TO-247/HV) | 1.13/10 | Nm/lb.in |
| Weight | TO-263HV | 2.5 | g |
| | TO-247/HV | 6.0 | g |

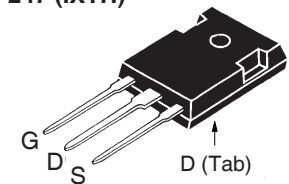
TO-263HV (IXTA)



TO-247HV (IXTH)



TO-247 (IXTH)



G = Gate D = Drain
S = Source Tab = Drain

Features

- High Blocking Voltage
- High Voltage Packages

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- High Voltage Power Supplies
- Capacitor Discharge Applications
- Pulse Circuits
- Laser and X-Ray Generation Systems

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|--------------|---|-----------------------|------|--------------------------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0V$, $I_D = 250\mu\text{A}$ | 2000 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$ | 2.0 | | 4.0 V |
| I_{GSS} | $V_{GS} = \pm 20V$, $V_{DS} = 0V$ | | | ± 100 nA |
| I_{DSS} | $V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_J = 125^\circ\text{C}$ | | | 5 μA 100 μA |
| $R_{DS(on)}$ | $V_{GS} = 10V$, $I_D = 0.5A$, Note 1 | | | 40 Ω |



IXTH1N200P3

IXTA1N200P3HV

IXTH1N200P3HV

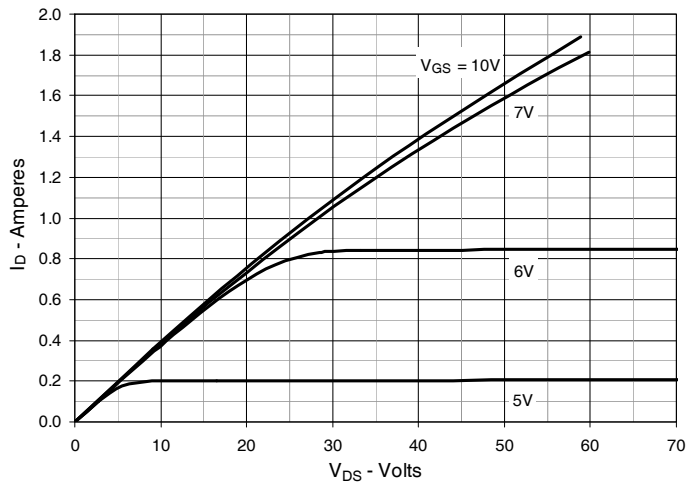
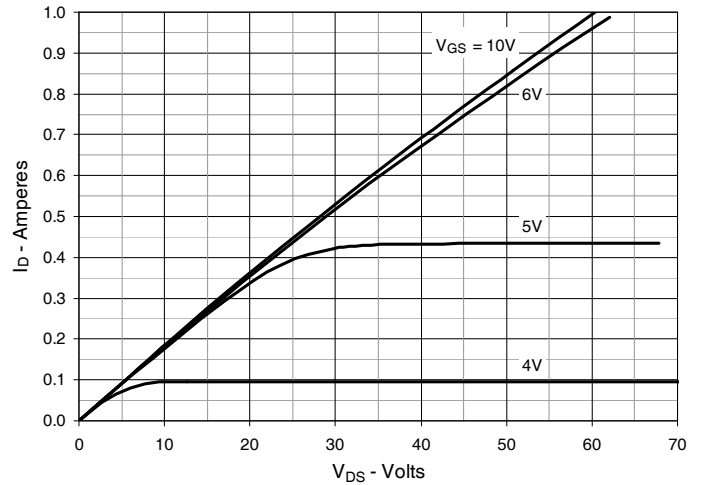
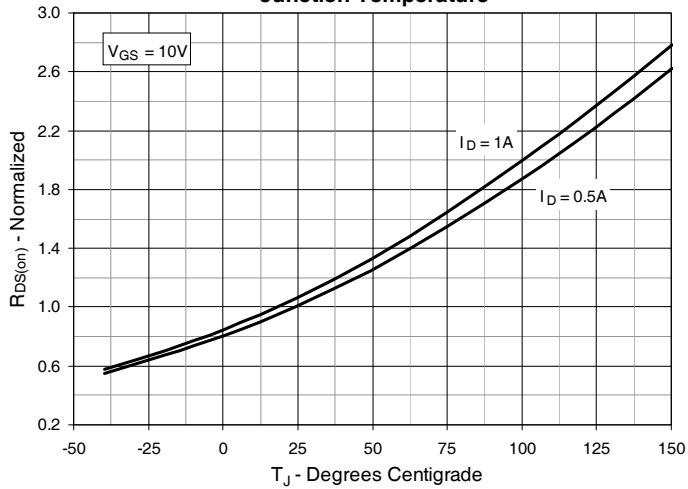
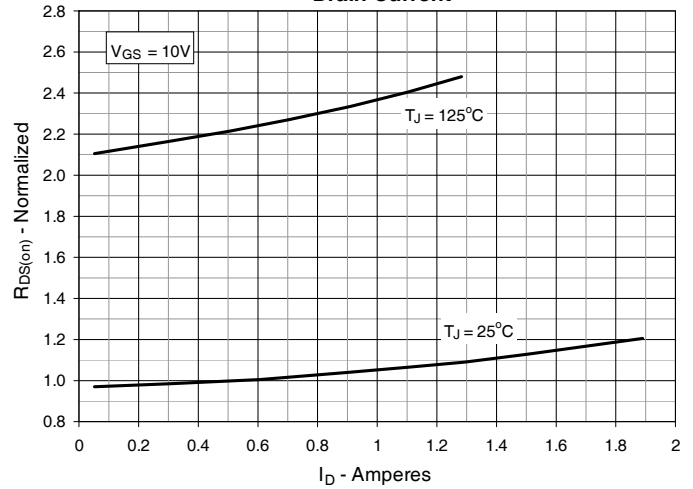
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 2. Output Characteristics @ $T_J = 125^\circ\text{C}$ Fig. 3. $R_{DS(on)}$ Normalized to $I_D = 0.5\text{A}$ Value vs. Junction TemperatureFig. 4. $R_{DS(on)}$ Normalized to $I_D = 0.5\text{A}$ Value vs. Drain Current

Fig. 5. Maximum Drain Current vs. Case Temperature

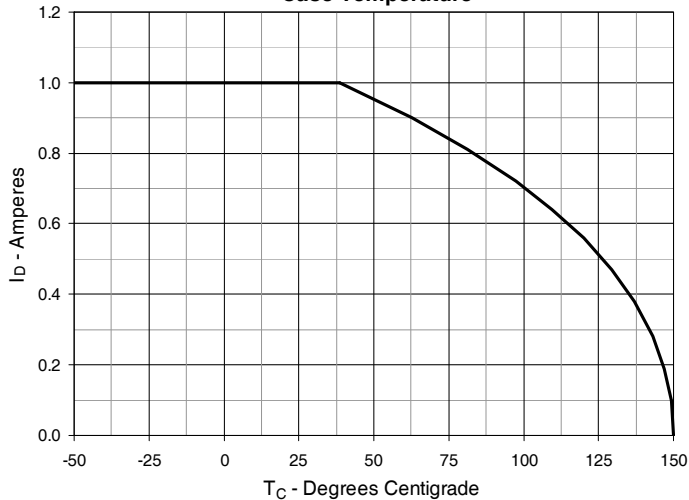


Fig. 6. Input Admittance

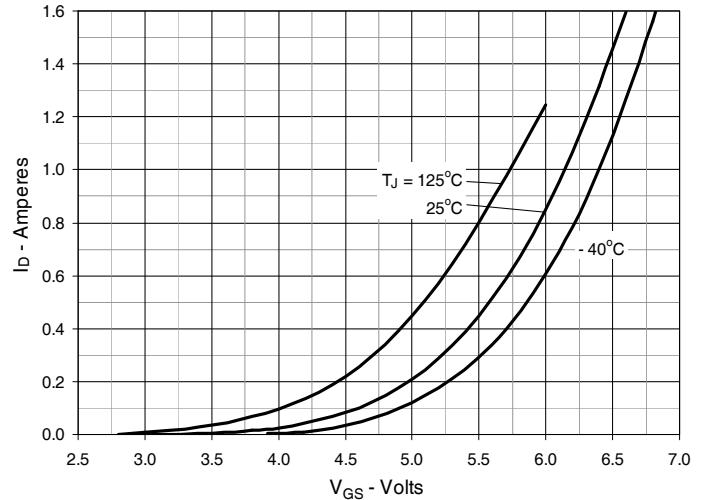


Fig. 7. Transconductance

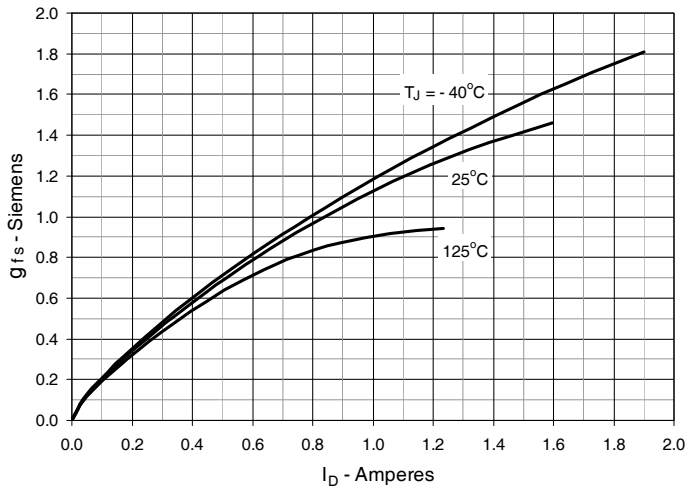


Fig. 8. Forward Voltage Drop of Intrinsic Diode

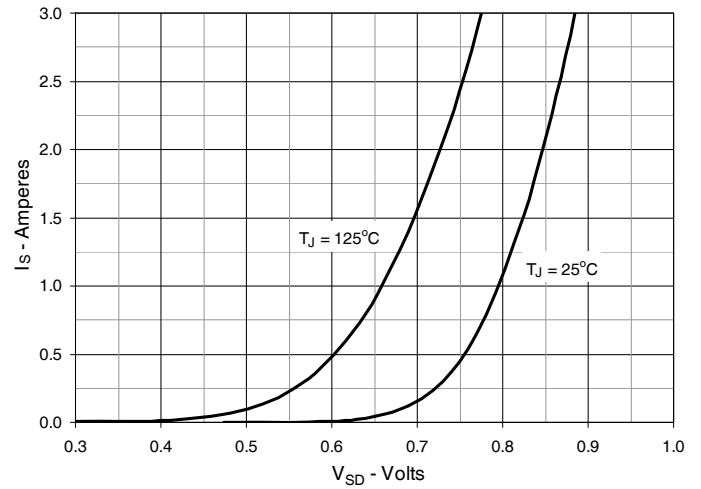


Fig. 9. Gate Charge

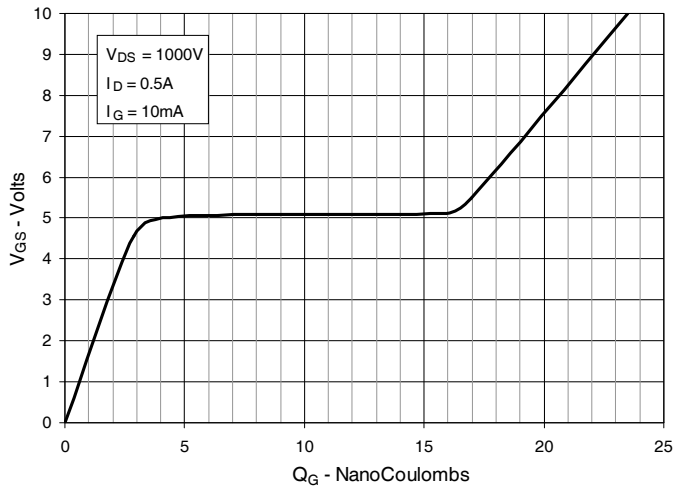


Fig. 10. Capacitance

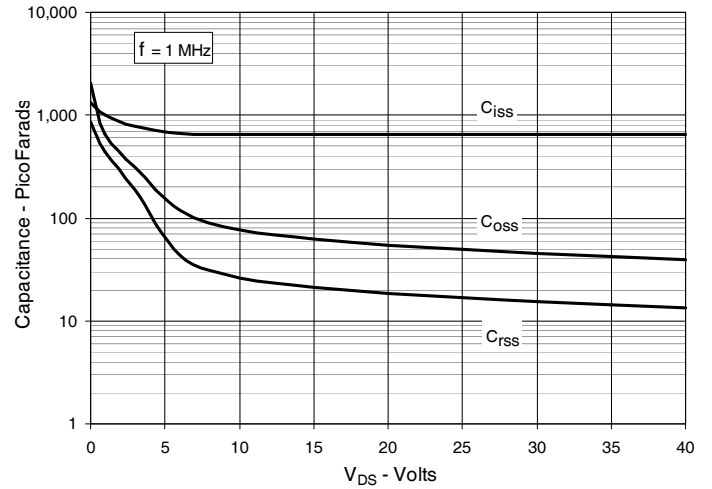
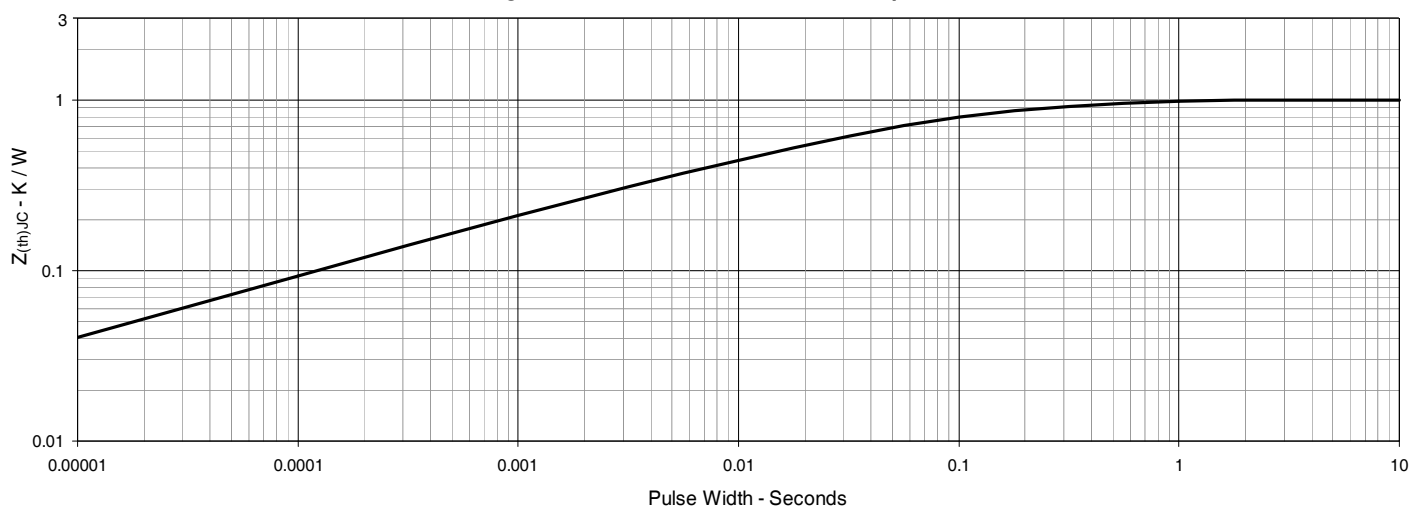


Fig. 11. Maximum Transient Thermal Impedance





IXTH1N200P3

IXTA1N200P3HV

IXTH1N200P3HV

Fig. 12. Forward-Bias Safe Operating Area
@ $T_C = 25^\circ\text{C}$

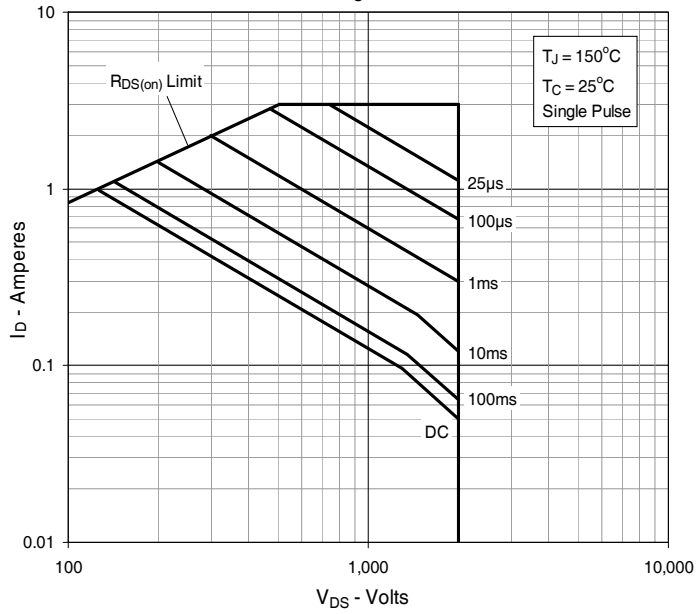
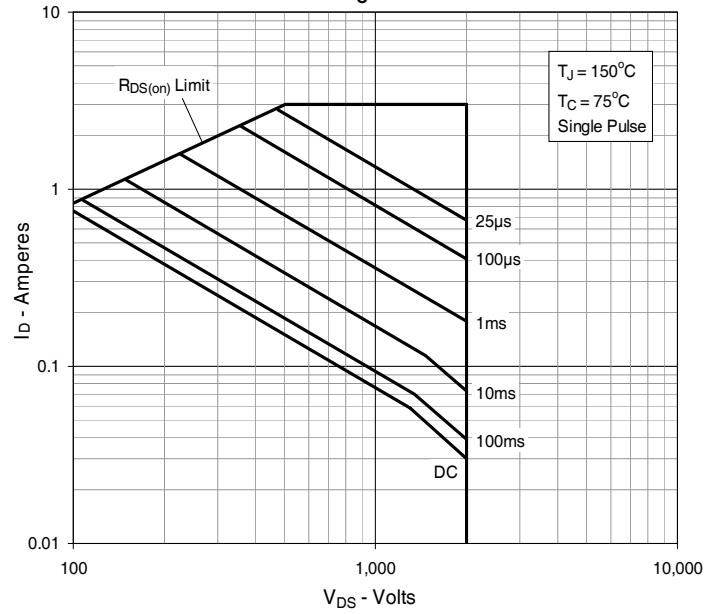


Fig. 13. Forward-Bias Safe Operating Area
@ $T_C = 75^\circ\text{C}$





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